

**EPOXY MOLDING COMPOUNDS WITH
RESISTANCE TO UV LIGHT AND HEAT**

ABSTRACT

A molding compound is provided for use in encapsulating electronic packages which include an optoelectronic component, such as an LED. The molding compound includes a partially cured epoxy composition, an antioxidant, and, optionally, a phosphor material substantially uniformly distributed throughout the epoxy composition. The optional phosphor material may be suspended within the epoxy composition by pre-reacting a portion of the epoxy composition prior to B-staging of the molding compound. As such, the optional phosphor material is suspended within the epoxy composition, thereby preventing settling of the phosphor material during B-staging, as well as during curing of the molding compound in the encapsulation process.